



Material Content Data Sheet



Sales Product Name		ICE2A280Z		Issued		29. August 2013		
MA#		MA001086348						
Package		PG-DIP-7-4		Weight*		653.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.640	1.32	1.32	13215	13215
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		74	
	non noble metal	zinc	7440-66-6	0.194	0.03		297	
	non noble metal	iron	7439-89-6	3.884	0.59		5942	
wire	non noble metal	copper	7440-50-8	157.726	24.13	24.76	241253	247566
	noble metal	gold	7440-57-5	0.205	0.03	0.03	313	313
	encapsulation	organic material	carbon black	1333-86-4	1.415	0.22		2165
encapsulation	plastics	epoxy resin	-	45.757	7.00		69989	
	inorganic material	silicondioxide	60676-86-0	424.551	64.93	72.15	649382	721536
leadfinish	non noble metal	tin	7440-31-5	6.460	0.99	0.99	9880	9880
plating	noble metal	silver	7440-22-4	1.911	0.29	0.29	2923	2923
glue	plastics	epoxy resin	-	0.448	0.07		685	
	noble metal	silver	7440-22-4	2.538	0.39	0.46	3882	4567
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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